2SC1980

Silicon NPN epitaxial planar type

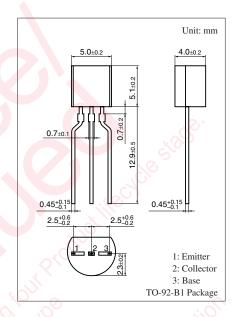
For high breakdown voltage low-noise amplification Complementary to 2SA0921

■ Features

- ullet High collector-emitter voltage (Base open) V_{CEO}
- Low noise voltage NV

■ Absolute Maximum Ratings $T_a = 25$ °C

g Unit
V
V
V
mA
mA
mW
°C
150 °C



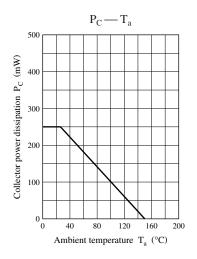
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

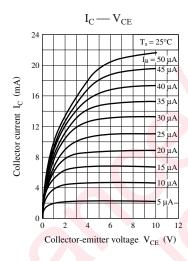
Parameter	Symbol	Conditions Mir		Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \mu\text{A}, I_E = 0$ 120		95		V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 1 \text{ mA}, I_B = 0$ 120				V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu\text{A}, I_C = 0$ 7				V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 50 \text{ V}, I_{E} = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 50 \text{ V}, I_{B} = 0$			1	μΑ
Forward current transfer ratio *	h_{FE}	$V_{CE} = 5 \text{ V}, I_C = 2 \text{ mA}$ 180			700	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 20 \text{ mA}, I_B = 2 \text{ mA}$			0.6	V
Transition frequency	f_T	$V_{CB} = 5 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$ 200			MHz	
Noise voltage	NV	$V_{CE} = 40 \text{ V}, I_C = 1 \text{ mA}, G_V = 80 \text{ dB}$ $R_g = 100 \text{ k}\Omega, \text{Function} = \text{FLAT}$		150	mV	

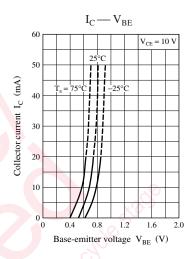
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

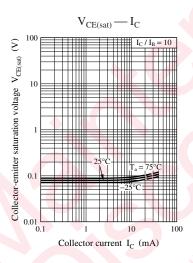
2. *: Rank classification

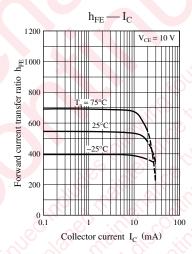
Rank	R	S	Т
h_{FE}	180 to 360	260 to 520	360 to 700

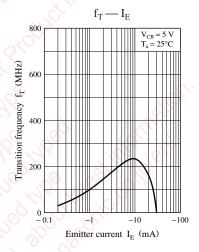


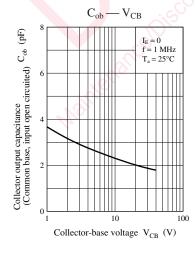


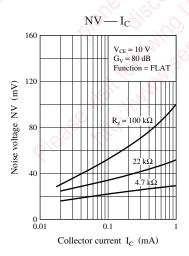












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